

# 50-MHz Low-Distortion High-CMRR Rail-to-Rail I/O, Single-Supply Operational Amplifier

Check for Samples: OPA365-EP

#### **FEATURES**

· Gain Bandwidth: 50 MHz

Zero-Crossover Distortion Topology

Excellent THD+N: 0.0004%

- CMRR: 96.5 dB (Min)

- Rail-to-Rail Input and Output

- Input 100 mV Beyond Supply Rail

Low Noise: 4.5 nV/√Hz at 100 kHz

Slew Rate: 25 V/µs

Fast Settling: 0.3 µs to 0.01%

Precision

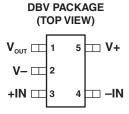
 Low Offset: 100 μV (Typical at 25°C)

- Low Input Bias Current: 0.2 pA

(Typical at 25°C) 2.2-V to 5.5-V Operation

# SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- · One Assembly/Test Site
- · One Fabrication Site
- Available in Military (–55°C/125°C), Temperature Range<sup>(1)</sup>
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability



(1) Additional temperature ranges available - contact factory

## **DESCRIPTION**

The OPA365 zero-crossover series, rail-to-rail, high-performance, CMOS operational amplifier is optimized for very low voltage, single-supply applications. Rail-to-rail input/output, low-noise (4.5 nV/√Hz) and high-speed operation (50-MHz gain bandwidth) make this device ideal for driving sampling analog-to-digital converters (ADCs). The OPA365 supports audio, signal conditioning, sensor amplification, defense, aerospace and medical applications. The OPA365 is also well-suited for cell phone power amplifier control loops.

Special features include an excellent common-mode rejection ratio (CMRR), no input stage crossover distortion, high input impedance, and rail-to-rail input and output swing. The input common-mode range includes both the negative and positive supplies. The output voltage swing is within 10mV of the rails.

The OPA365 is available in the SOT23-5 package and is specified for operation from −55°C to 125°C.

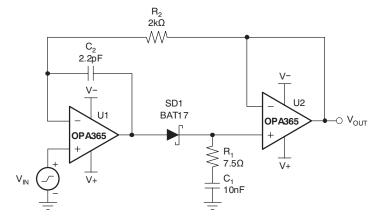


Figure 1. Fast Settling Peak Detector



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## ORDERING INFORMATION(1)

T <sub>A</sub>	PACKAGE	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
–55°C to 125°C	SOT23 – DBV	OPA365AMDBVTEP	OUNM		

<sup>(1)</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

## **ABSOLUTE MAXIMUM RATINGS**(1)

$V_{CC}$	Supply voltage		5.5 V
VI	Signal input terminals, voltage (2)		(V-) - 0.5V to (V+) + 0.5 V
I <sub>I</sub>	Signal input terminals, current <sup>(2)</sup>		±10 mA
tosc	Output short-circuit duration (3)(4)		Continuous
T <sub>OP</sub>	Operating temperature		−55°C to 125°C
T <sub>stg</sub>	Storage temperature		−65°C to 150°C
$T_{J}$	Junction temperature		150°C
		Human Body Model	4000V
ESD	Electrostatic discharge rating	Charged Device Model	1000V
<u> </u>		Machine Model	200V

<sup>(1)</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(3) Short-circuit to ground, one amplifier per package

(4) Continuous output current greater than 20 mA for extended periods may affect product reliability.

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<sup>(2)</sup> Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.

#### **ELECTRICAL CHARACTERISTICS**

 $V_c = 2.2 \text{ V}$  to 5.5 V,  $R_t = 10 \text{ kO}$  connected to  $V_c/2$ ,  $V_{cM} = V_c/2$ , and  $V_{cMT} = V_c/2$  (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	T <sub>A</sub> <sup>(1)</sup>	MIN	TYP	MAX	UNIT		
OFFSE1	Γ VOLTAGE								
V <sub>OS</sub>	Input offset voltage		25°C Full range		100	200 450	μV		
dV <sub>OS</sub> / dT	Input offset voltage drift		Full range		3		μV/°C		
PSRR	Input offset voltage vs power supply	V <sub>S</sub> = +2.2V to +5.5V	Full range		10	100	μV/V		
INPUT E	BIAS CURRENT		<u> </u>	•					
	Innut high augrent		25°C		±0.2	±10	pА		
I <sub>B</sub>	Input bias current		Full range	See Typical Characteristics					
Ios	Input offset current		25°C		±0.2	±10	рА		
NOISE									
e <sub>n</sub>	Input voltage noise	f = 0.1Hz to 10Hz	25°C		5		$\mu V_{PP}$		
e <sub>n</sub>	Input voltage noise density	f = 100kHz	25°C		4.5		nV/√Hz		
i <sub>n</sub>	Input current noise density	f = 10kHz	25°C		4		fA/√Hz		
INPUT V	OLTAGE RANGE								
V <sub>CM</sub>	Common-mode voltage range		Full range	(V-) – 0.1		(V+) + 0.1	V		
CMRR	Common-mode rejection ratio	$(V-) - 0.1V \le V_{CM} \le (V+) + 0.1V$	Full range	96.5	120		dB		
INPUT (	CAPACITANCE								
	Differential		25°C		6		pF		
	Common-mode		25°C		2		pF		
OPEN-L	OOP GAIN								
		$R_L = 10k\Omega$ , $100mV < V_O < (V+) - 100mV$	Full range	96.5	120				
$A_{OL}$	Open-loop voltage gain	$R_L = 600\Omega$ , $200 \text{mV} < V_O < (V+) - 200 \text{mV}$	25°C	100	120		dB		
		$R_L = 600\Omega$ , $200\text{mV} < V_O < (V+) - 200\text{mV}$ Full range		91					
FREQUI	ENCY RESPONSE		·						
GBW	Gain-bandwidth product		25°C		50		MHz		
SR	Slew rate	V <sub>S</sub> = 5V, G = +1	25°C		25		V/µs		
	Cattliantina	0.1%, V <sub>S</sub> = 5V, 4V Step, G = +1	25°C		200				
t <sub>S</sub>	Settling time	0.01%, V <sub>S</sub> = 5V, 4V Step, G = +1	25°C		300		ns		
	Overload recovery time	V <sub>S</sub> = 5V, V <sub>IN</sub> x Gain > V <sub>S</sub>	25°C		< 0.1		μs		
THD+N	Total harmonic distortion + noise (2)	$V_S = 5V$ , $R_L = 600\Omega$ , $V_O = 4VPP$ , $G = +1$ , $f = 1kHz$	25°C		0.0004		%		
OUTPU	Т								
	Voltage output swing from rail	$R_L = 10k\Omega, V_S = 5.5V$	Full range		10	20	mV		
I <sub>SC</sub>	Short-circuit current (3)		25°C		±65		mA		
C <sub>L</sub>	Capacitive load drive		25°C	See Typical Characteristics					
	Open-loop output impedance	f = 1MHz, I <sub>O</sub> = 0	1MHz, I <sub>O</sub> = 0 25°C 30				Ω		
POWER	SUPPLY								
Vs	Specified voltage range		Full range	2.2		5.5	V		
	Quiescent current per	I <sub>O</sub> = 0	25°C		4.6	5			
	amplifier	Full range				5.5	mA		

Full range  $T_A = -55^{\circ}C$  to +125°C Third-order filter, bandwidth 80kHz at -3dB.

Continuous output current greater than 20 mA for extended periods may affect product reliability.



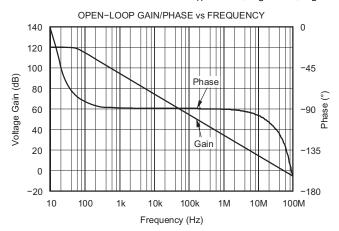
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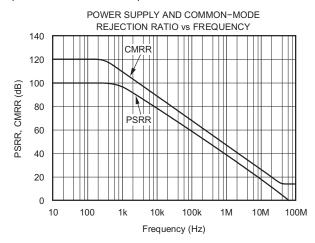
 $V_S$  = 2.2 V to 5.5 V,  $R_L$  = 10 k $\Omega$  connected to  $V_S/2$ ,  $V_{CM}$  =  $V_S/2$ , and  $V_{OUT}$  =  $V_S/2$  (unless otherwise noted)

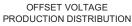
O	· =	0 , 0111 0 , 001	J (		,		
	PARAMETER	TEST CONDITIONS	T <sub>A</sub> <sup>(1)</sup>	MIN	TYP	MAX	UNIT
TEMPE	RATURE RANGE						
	Specified range			<b>–</b> 55		125	°C
$\theta_{JA}$	Thermal resistance				200		°C/W

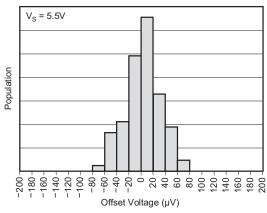
#### TYPICAL CHARACTERISTICS

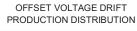
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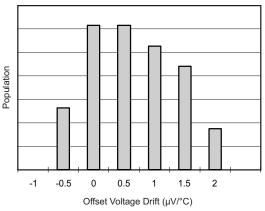


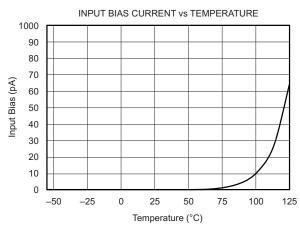


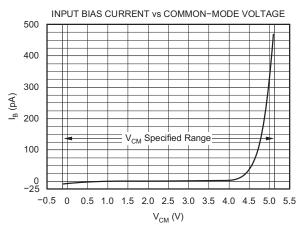








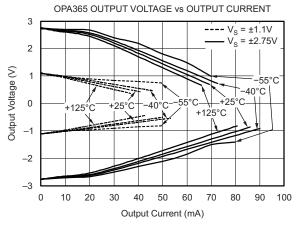


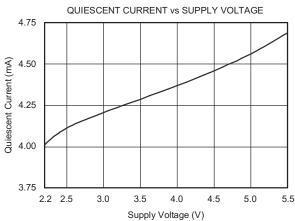


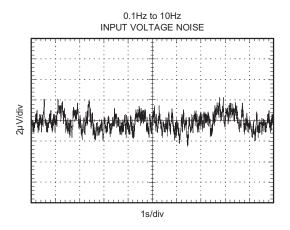


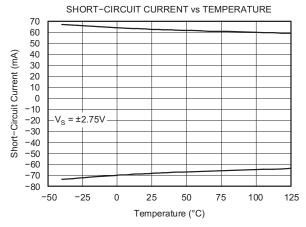
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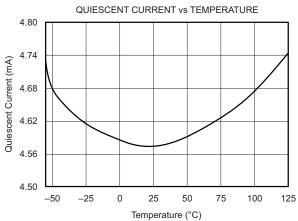
 $T_A = 25$ °C,  $V_S = 5$  V,  $C_L = 0$  pF (unless otherwise noted)

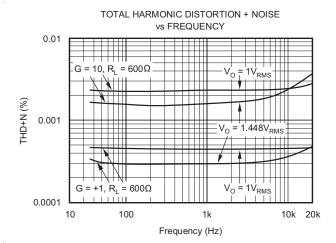






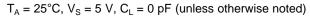


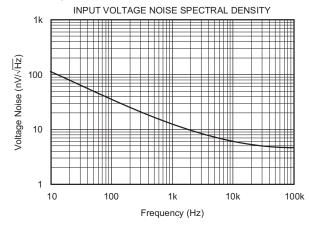


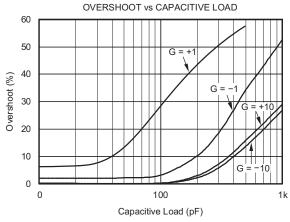


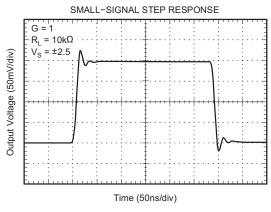


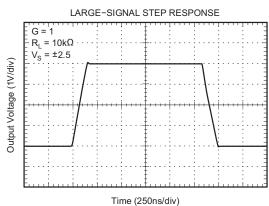
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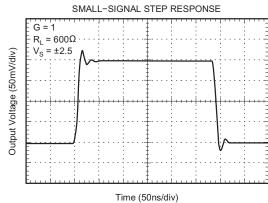


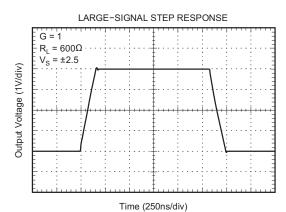














#### APPLICATION INFORMATION

### **Operating Characteristics**

The OPA365 amplifier parameters are fully specified from 2.2 V to 5.5 V. Many of the specifications apply from −55°C to 125°C. Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in *Typical Characteristics*.

## **General Layout Guidelines**

The OPA365 is a wideband amplifier. To realize the full operational performance of the device, good high-frequency printed circuit board (PCB) layout practices are required. Low-loss 0.1-µF bypass capacitors must be connected between each supply pin and ground as close to the device as possible. The bypass capacitor traces should be designed for minimum inductance.

## **Basic Amplifier Configurations**

As with other single-supply op amps, the OPA365 may be operated with either a single supply or dual supplies (see Figure 2). A typical dual-supply connection is shown in Figure 2, which is accompanied by a single-supply connection. The OPA365 is configured as a basic inverting amplifier with a gain of -10 V/V. The dual-supply connection has an output voltage centered on zero, while the single-supply connection has an output centered on the common-mode voltage  $V_{CM}$ . For the circuit shown, this voltage is 1.5 V, but may be any value within the common-mode input voltage range. The OPA365  $V_{CM}$  range extends 100 mV beyond the power-supply rails.

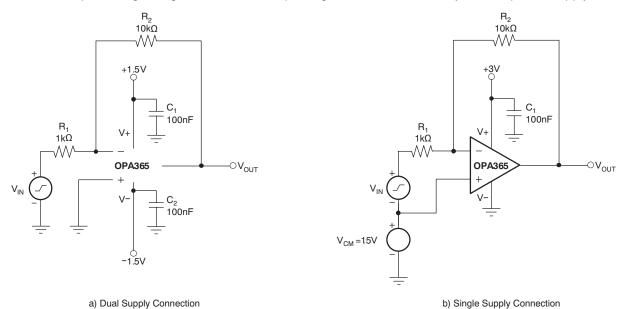


Figure 2. Basic Circuit Connections

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Figure 3 shows a single-supply, electret microphone application where  $V_{CM}$  is provided by a resistive divider. The divider also provides the bias voltage for the electret element.

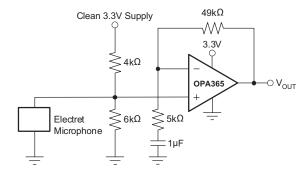
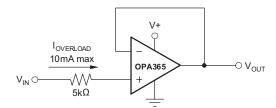


Figure 3. Microphone Preamplifier

### Input and ESD Protection

The OPA365 incorporates internal electrostatic discharge (ESD) protection circuits on all pins. In the case of input and output pins, this protection primarily consists of current steering diodes connected between the input and power-supply pins. These ESD protection diodes also provide in-circuit, input overdrive protection, provided that the current is limited to 10 mA as stated in the Absolute Maximum Ratings. Figure 4 shows how a series input resistor may be added to the driven input to limit the input current. The added resistor contributes thermal noise at the amplifier input and its value should be kept to the minimum in noise-sensitive applications.



**Figure 4. Input Current Protection** 

# TEXAS INSTRUMENTS

#### Rail-to-Rail Input

The OPA365 features true rail-to-rail input operation, with supply voltages as low as ±1.1 V (2.2 V). A unique zero-crossover input topology eliminates the input offset transition region typical of many rail-to-rail, complementary stage operational amplifiers. This topology also allows the OPA365 to provide superior common-mode performance over the entire input range, which extends 100 mV beyond both power-supply rails, as shown in Figure 5. When driving ADCs, the highly linear VCM range of the OPA365 assures that the op amp/ADC system linearity performance is not compromised.

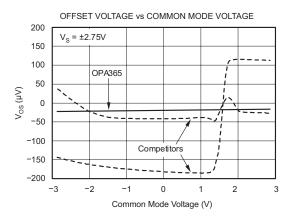


Figure 5. OPA365 has Linear Offset Over the Entire Common-Mode Range

A simplified schematic illustrating the rail-to-rail input circuitry is shown in Figure 6.

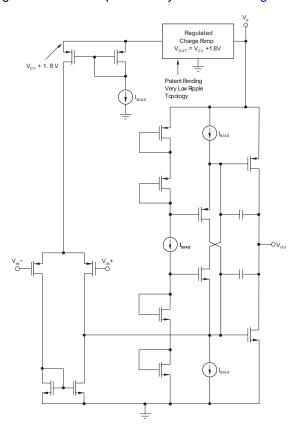


Figure 6. Simplified Schematic



#### **Capacitive Loads**

The OPA365 may be used in applications where driving a capacitive load is required. As with all op amps, there may be specific instances where the OPA365 can become unstable, leading to oscillation. The particular op amp circuit configuration, layout, gain and output loading are some of the factors to consider when establishing whether an amplifier will be stable in operation. An op amp in the unity-gain (1 V/V) buffer configuration and driving a capacitive load exhibits a greater tendency to be unstable than an amplifier operated at a higher noise gain. The capacitive load, in conjunction with the op amp output resistance, creates a pole within the feedback loop that degrades the phase margin. The degradation of the phase margin increases as the capacitive loading increases.

When operating in the unity-gain configuration, the OPA365 remains stable with a pure capacitive load up to approximately 1 nF. The equivalent series resistance (ESR) of some very large capacitors ( $C_L > 1~\mu F$ ) is sufficient to alter the phase characteristics in the feedback loop such that the amplifier remains stable. Increasing the amplifier closed-loop gain allows the amplifier to drive increasingly larger capacitance. This increased capability is evident when observing the overshoot response of the amplifier at higher voltage gains. See the typical characteristic graph, Small-Signal Overshoot vs. Capacitive Load.

One technique for increasing the capacitive load drive capability of the amplifier operating in unity gain is to insert a small resistor, typically 10  $\Omega$  to 20  $\Omega$ , in series with the output; see Figure 7. This resistor significantly reduces the overshoot and ringing associated with large capacitive loads. A possible problem with this technique is that a voltage divider is created with the added series resistor and any resistor connected in parallel with the capacitive load. The voltage divider introduces a gain error at the output that reduces the output swing. The error contributed by the voltage divider may be insignificant. For instance, with a load resistance,  $R_L = 10 \text{ k}\Omega$ , and  $R_S = 20 \Omega$ , the gain error is only about 0.2%. However, when  $R_L$  is decreased to 600  $\Omega$ , which the OPA365 is able to drive, the error increases to 7.5%.

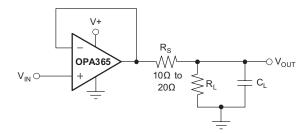


Figure 7. Improving Capacitive Load Drive



### Achieving an Output Level of Zero Volts (0V)

Certain single-supply applications require the op amp output to swing from 0 V to a positive full-scale voltage and have high accuracy. An example is an op amp employed to drive a single-supply ADC having an input range from 0 V to 5 V. Rail-to-rail output amplifiers with very light output loading may achieve an output level within millivolts of 0 V (or  $+V_S$  at the high end), but not 0 V. Furthermore, the deviation from 0V only becomes greater as the load current required increases. This increased deviation is a result of limitations of the CMOS output stage.

When a pulldown resistor is connected from the amplifier output to a negative voltage source, the OPA365 can achieve an output level of 0 V, and even a few millivolts below 0 V. Below this limit, nonlinearity and limiting conditions become evident. Figure 8 illustrates a circuit using this technique.

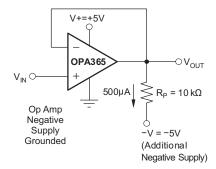


Figure 8. Swing-to-Ground

A pulldown current of approximately 500  $\mu$ A is required when OPA365 is connected as a unity-gain buffer. A practical termination voltage (V<sub>NEG</sub>) is -5 V, but other convenient negative voltages also may be used. The pulldown resistor R<sub>L</sub> is calculated from R<sub>L</sub> = [(V<sub>O</sub> -V<sub>NEG</sub>)/(500  $\mu$ A)]. Using a minimum output voltage (V<sub>O</sub>) of 0 V, R<sub>L</sub> = [0 V-(-5 V)]/(500  $\mu$ A)] = 10 k $\Omega$ . Keep in mind that lower termination voltages result in smaller pulldown resistors that load the output during positive output voltage excursions.

Note that this technique does not work with all op amps and should only be applied to op amps such as the OPA365 that have been specifically designed to operate in this manner. Also, operating the OPA365 output at 0 V changes the output stage operating conditions, resulting in somewhat lower open-loop gain and bandwidth. Keep these precautions in mind when driving a capacitive load because these conditions can affect circuit transient response and stability.

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#### **Active Filtering**

The OPA365 is well-suited for active filter applications requiring a wide bandwidth, fast slew rate, low-noise, single-supply operational amplifier. Figure 9 shows a 500-kHz, 2nd-order, low-pass filter utilizing the multiple-feedback (MFB) topology. The components have been selected to provide a maximally-flat Butterworth response. Beyond the cutoff frequency, roll-off is -40 dB/dec. The Butterworth response is ideal for applications requiring predictable gain characteristics such as the anti-aliasing filter used ahead of an ADC.

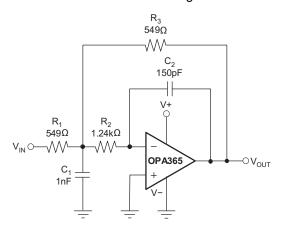


Figure 9. Second-Order Butterworth 500kHz Low-Pass Filter

One point to observe when considering the MFB filter is that the output is inverted, relative to the input. If this inversion is not required, or not desired, a noninverting output can be achieved through one of these options: 1) adding an inverting amplifier; 2) adding an additional 2nd-order MFB stage; or 3) using a noninverting filter topology such as the Sallen-Key (shown in Figure 10). MFB and Sallen-Key, low-pass and high-pass filter synthesis is quickly accomplished using TI's FilterPro program. This software is available as a free download at www.ti.com.

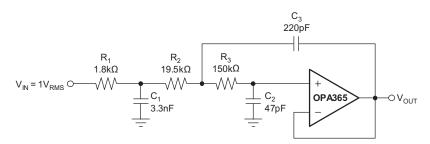


Figure 10. Configured as a 3-Pole, 20kHz, Sallen-Key Filter

## **Driving an Analog-to-Digital Converter**

Very wide common-mode input range, rail-to-rail input and output voltage capability and high speed make the OPA365 an ideal driver for modern ADCs. Also, because it is free of the input offset transition characteristics inherent to some rail-to-rail CMOS op amps, the OPA365 provides low THD and excellent linearity throughout the input voltage swing range. Figure 11 shows the OPA365 driving an ADS8326, 16-bit, 250kSPS converter. The amplifier is connected as a unity-gain, noninverting buffer and has an output swing to 0 V, making it directly compatible with the ADC minus full-scale input level. The 0-V level is achieved by powering the OPA365 V−pin with a small negative voltage established by the diode forward voltage drop. A small, signal-switching diode or Schottky diode provides a suitable negative supply voltage of −0.3 V to −0.7 V. The supply rail-to-rail is equal to V+, plus the small negative voltage.



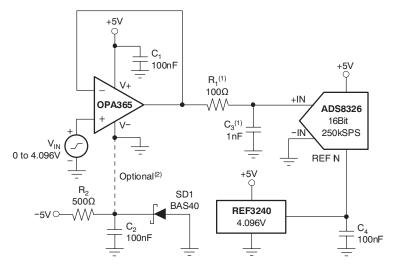


Figure 11. Driving the ADS8326

One method for driving an ADC that negates the need for an output swing down to 0 V uses a slightly compressed ADC full-scale input range (FSR). For example, the 16-bit ADS8361 (shown in Figure 12) has a maximum FSR of 0 V to 5 V, when powered by a 5-V supply and  $V_{REF}$  of 2.5 V. The idea is to match the ADC input range with the op amp full linear output swing range; for example, an output range of 0.1 V to 4.9 V. The reference output from the ADS8361 ADC is divided down from 2.5 V to 2.4 V using a resistive divider. The ADC FSR then becomes  $4.8V_{PP}$  centered on a common-mode voltage of 2.5 V. Current from the ADS8361 reference pin is limited to about  $\pm 10~\mu$ A. Here,  $5~\mu$ A was used to bias the divider. The resistors must be precise to maintain the ADC gain accuracy. An additional benefit of this method is the elimination of the negative supply voltage; it requires no additional power-supply current.

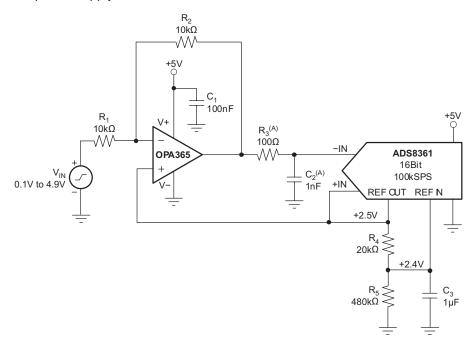


Figure 12. Driving the ADS8361

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An RC network, consisting of R1 and C1, is included between the op amp and the ADS8361. It not only provides a high-frequency filter function, but more importantly serves as a charge reservoir used for charging the converter internal hold capacitance. This capability assures that the op amp output linearity is maintained as the ADC input characteristics change throughout the conversion cycle. Depending on the particular application and ADC, some optimization of the R1 and C1 values may be required for best transient performance.





11-Apr-2013

#### PACKAGING INFORMATION

Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
OPA365AMDBVTEP	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	OUNM	Samples
V62/11610-01XE	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	OUNM	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

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#### OTHER QUALIFIED VERSIONS OF OPA365-EP:

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.



# **PACKAGE OPTION ADDENDUM**



www.ti.com 11-Apr-2013

• Automotive: OPA365-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

DBV (R-PDSO-G5)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



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